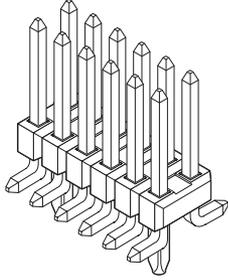


# 2.54mm (.100") Pitch C-Grid® Breakaway Header

**71308**

**Dual Row, SMT, Vertical  
With or Without Peg**



### Features and Benefits

- Available with or without retention pegs
- Gull wing surface mount tails
- Vapor phase/IR reflow process compatible
- Stackable end-to-end (on unbroken edges)
- Drawn .025" square wire provides 4-sided smooth interface

### Reference Information

Product Specification: PS-71308  
 Packaging: Tube or tape and reel\*  
 UL File No.: E29179  
 CSA File No.: LR19980  
 Mates With: 7859 Shunts, C-Grid Receptacles, SL Crimp,  
 FFC and IDT Housings  
 Designed In: Inches

\* Contact Molex for tape and reel order numbers

### Electrical

Voltage: 250V  
 Current: 3.0A  
 Contact Resistance: 15 milliohms max.  
 Dielectric Withstanding Voltage: 1500V  
 Insulation Resistance: 1000 Megohms min.

### Mechanical

Pin Retention to Header: 17.79N (4 lb)  
 Insertion Force to PCB: 35.58N (8 lb) per peg  
 Durability: Tin—25 cycles; Gold—50 cycles

### Physical

Housing: Black high-temperature thermal plastic, UL 94V-0  
 Contact: Copper Alloy  
 Plating: See Table  
 Operating Temperature: -40 to +105°C  
 Screened Paste Thickness: .010 to .015"

**Not For Use With Molex C-Grid III™ Components**

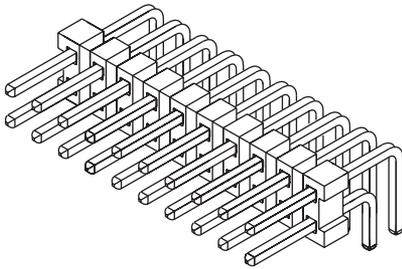
Plating Option	Order No.		Lead-free
	Without PCB Retention Pegs	With PCB Retention Pegs	
150µ" Tin	15-91-2XX0	15-91-1XX1	Yes
15µ" Gold	15-91-0XX0	15-91-1XX2	
30µ" Gold	15-91-3XX0	15-91-1XX3	

Replace XX with no. of circuits, 04-80 (even only). See Sales drawing for 82-100.

# 2.54mm (.100") C-Grid® Breakaway Header

**71764**

**Low Profile, Dual Row  
Right Angle,  
High-Temperature**



### Features and Benefits

- Sizes 4 to 30 circuits
- Low profile: .200" high
- Stackable end-to-end (on unbroken edges)
- Easy breakaway to smaller sizes
- Drawn .025" square wire provides 4-sided smooth surface for quality interface
- High-temperature wafer for SMT compatibility

### Reference Information

Product Specification: PS-71764  
 Packaging: Tube  
 UL File No.: E29179  
 Mates With: 7859 Shunts, C-Grid Receptacles, SL Crimp,  
 FFC and IDT Housings  
 Designed In: Inches

### Electrical

Voltage: 250V  
 Current: 3.0A  
 Contact Resistance: 15 milliohms max.  
 Dielectric Withstanding Voltage: 1500V  
 Insulation Resistance: 1000 Megohms min.

### Mechanical

Pin Retention to Header: 17.79N (4 lb)  
 Durability: Tin—25 cycles; Gold—50 cycles

### Physical

Housing: Black high-temperature thermal plastic, UL 94V-0  
 Contact: Copper Alloy  
 Plating: See Table  
 Operating Temperature: -40 to +105°C

**Not For Use With Molex C-Grid III™ Components**

Plating Option	Order No.	Lead-free
15µ" min. select Gold	71764-01XX	Yes
30µ" min. select Gold	71764-02XX	
150µ" Tin/Lead, Nickel overall	71764-00XX	

Replace XX with no. of circuits, 04-30 (even only)

2.54mm (.100") Pitch PCB and Wire Connectors